Robotechnik (300757 CH)

Initiate at Buy: Smart move; it's all about photonics

Equities
Machinery

China

- Robotechnik has switched its focus from solar cells to high-tech photonics; customers include TSMC and Nvidia
- Strong order flow reflects strong demand and provides earnings visibility; growth potential not fully priced in
- We forecast a 330% 2026-28 net profit CAGR; initiate at Buy with a PEG-based TP of RMB758.00

New strategy. Robotechnik's legacy solar cell business is slowing. In May 2025 the company completed the RMB1bn acquisition of ficonTEC, a leading automated machine maker for the assembly, coupling, and testing of specialised optical components increasingly used in AI, which is based in Germany. Customers include TSMC, Broadcom, Nvidia, and Valeo. We believe the high-margin photonics business will grow quickly and account for c90% of revenue by 2028e (vs 46% of revenue in 2025).

Riding the photonics wave to mass production. With advanced photonics packaging approaching mass production, we expect increasing demand for high-volume assembly, packaging and testing machines to meet customers' stringent demand for yield and throughput. ficonTEC has over 20 years of expertise in high-precision photonic coupling and alignment, motion control and automation integration. *Exhibits 4-5* show that the company has a leading position in this highly specialised optical field, where few players possess comparable end-to-end capabilities. We think the robust order momentum reflects strong and growing demand by global customers. More importantly, we believe Robotechnik can provide capital, manufacturing resources, and the supply chain leverage needed to scale ficonTEC revenue growth faster than peers with more competitive costs. Gross margin improved to 34.5% in 2025 from 23.8% in 2019, and we expect it to rise further to 49.7% in 2028e, driven by the higher-margin photonics packaging business.

Investor conviction subdued, potential not fully priced in. The market is still debating how soon photonics packaging will become commercialised. The stock corrected over 20% since its y-t-d high on 3 June (vs CSI: -6%) as AI names derated. We see re-rating opportunities from improving earnings visibility brought by a series of order wins; and the market's scepticism and below peer valuation creates an attractive entry point to gain exposure to a high-quality name in the global photonics industry.

Valuation and risks. We think 2027 will be the inflection year, with net profit growth accelerating to 518% y-o-y, driven by top line growth, gross margin expansion on higher optoelectronic product mix and the scale effect. We value the stock with a PEG approach. Global peers trade at an average 0.7x PEG (based on average 2027-28 consensus PE of 26x and 36% 2026-28 EPS CAGR). We forecast a 330% net profit CAGR in 2026-28e, implying a 231x PE; applying that to our average 2027-28e EPS of RMB3.29, we arrive at our TP of RMB758.00, implying c37% upside. We initiate with a Buy rating. **Key downside risks:** alternative coupling solutions, AI capex cuts, slower mass production, geopolitical risks, and price competition.

INITIATE AT BUY

TARGET PRICE (CNY)	PREVIOUS TARGET (CNY)
758.00	-
SHARE PRICE (CNY)	**UPSIDE/DOWNSIDE**
552.11 (as of 27 Aug 2026)	**+37.3%**

MARKET DATA

Market cap (CNYm)	92,538	Free float	56%
Market cap (USDm)	13,771	BBG	300757 CH
3m ADTV (USDm)	594	RIC	300757.SZ

FINANCIALS AND RATIOS (CNY)

Year to	12/2025a	12/2026e	12/2027e	12/2028e
HSBC QH EPS	-0.40	0.27	1.65	4.92
HSBC QH EPS prev	na	na	na	na
Change (%)	na	na	na	na
Consensus EPS	-0.31	0.74	3.75	6.02
PE (x)	nm	2069.3	334.9	112.2
Dividend yield (%)	0.0	0.0	0.0	0.0
EV/EBITDA (x)	1469.8	460.0	173.9	74.8
ROE (%)	-5.0	2.6	14.9	34.3

52-WEEK PRICE (CNY)



Source: LSEG IBES, HSBC Qianhai Securities estimates

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This report must be read with the disclosures and the analyst certifications in the Disclosure appendix, and with the Disclaimer, which forms part of it.

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Financials & valuation: Robotechnik

Buy

Financial statements

Year to	12/2025a	12/2026e	12/2027e	12/2028e
Profit & loss summary (CNYm)				
Revenue	950	1,244	2,298	4,054
EBITDA	64	202	532	1,226
Depreciation & amortisation	-55	-56	-60	-62
Operating profit/EBIT	8	146	472	1,164
Net interest	-34	-33	-29	-25
PBT	-71	49	301	899
HSBC Qianhai PBT	-71	49	301	899
Taxation	5	-4	-27	-81
Net profit	-66	45	276	825
HSBC Qianhai net profit	-66	45	276	825
Cash flow summary (CNYm)				
Cash flow from operations	208	324	447	793
Capex	-43	-87	-207	-203
Cash flow from investment	-674	-87	-207	-203
Dividends	-42	0	0	0
Change in net debt	287	-237	-240	-591
FCF equity	165	237	240	591
Balance sheet summary (CNYm)				
Intangible fixed assets	1,231	1,231	1,231	1,231
Tangible fixed assets	348	379	526	666
Current assets	1,783	1,950	2,170	3,297
Cash & others	284	600	640	1,231
Total assets	3,642	3,979	4,514	6,013
Operating liabilities	736	949	1,409	2,084
Gross debt	1,235	1,313	1,113	1,113
Net debt	950	713	473	-117
Shareholders' funds	1,673	1,718	1,994	2,820
Invested capital	2,341	2,010	1,878	1,878

Ratio, growth and per share analysis

Year to	12/2025a	12/2026e	12/2027e	12/2028e
Y-o-y % change				
Revenue	-14.1	31.0	84.7	76.4
EBITDA	-59.8	218.2	163.3	130.5
Operating profit	-93.5	1623.1	223.2	146.6
PBT	-218.1		518.0	198.6
HSBC Qianhai EPS	-196.2		518.0	198.6
Ratios (%)				
Revenue/IC (x)	0.5	0.6	1.2	2.2
ROIC	0.4	6.1	22.1	56.4
ROE	-5.0	2.6	14.9	34.3
ROA	-2.2	1.2	6.5	15.5
EBITDA margin	6.7	16.2	23.2	30.3
Operating profit margin	0.9	11.7	20.5	28.7
EBITDA/net interest (x)	1.9	6.1	18.7	50.0
Net debt/equity	56.9	41.6	23.8	-4.2
Net debt/EBITDA (x)	15.0	3.5	0.9	-0.1
CF from operations/net debt	21.9	45.5	94.4	
Per share data (CNY)				
EPS Rep (diluted)	-0.40	0.27	1.65	4.92
HSBC Qianhai EPS (diluted)	-0.40	0.27	1.65	4.92
DPS	0.00	0.00	0.00	0.00
Book value	9.98	10.25	11.90	16.82

Valuation data

Year to	12/2025a	12/2026e	12/2027e	12/2028e
EV/sales	98.3	74.7	40.3	22.6
EV/EBITDA	1469.8	460.0	173.9	74.8
EV/IC	39.9	46.2	49.3	48.8
PE*	nm	2069.3	334.9	112.2
PB	55.3	53.9	46.4	32.8
FCF yield (%)	0.2	0.3	0.3	0.6
Dividend yield (%)	0.0	0.0	0.0	0.0

* Based on HSBC Qianhai EPS (diluted)

ESG metrics

Environmental Indicators	12/2025a
GHG emission intensity*	n/a
Energy intensity*	n/a
CO_2 reduction policy	Yes
Social Indicators	**12/2025a**
Employee costs as % of revenues	n/a
Employee turnover (%)	n/a
Diversity policy	No

Governance Indicators	12/2025a
No. of board members	7
Average board tenure (years)	4.0
Female board members (%)	14.3
Board members independence (%)	42.9

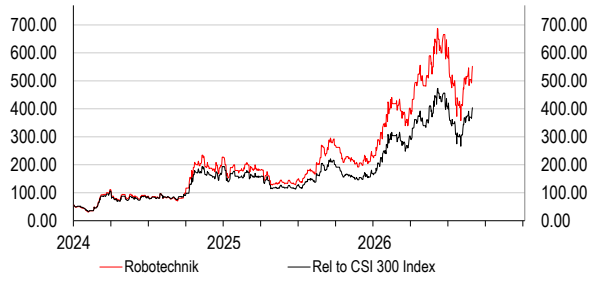
Source: Company data, HSBC Qianhai Securities

* GHG intensity and energy intensity are measured in kg and kWh respectively against revenue in USD '000s

Issuer information

Share price (CNY)	552.11	Free float	56%
Target price (CNY)	758.00	Sector	Machinery
RIC (Equity)	300757.SZ	Country/Region	China
Bloomberg (Equity)	300757 CH	Analyst	Amy Hu
Market cap (USDm)	13,771	Contact	+86 755 8898 3408

Price relative



Source: HSBC Qianhai Securities

Note: Priced at close of 27 Aug 2026

Investment summary

- 2027 set to be an inflection point for Robotechnik due to the commercialisation of advanced optical packaging
- The company's high-volume coupling and testing machines ease manufacturing bottlenecks, with little competition
- We forecast a 2026-28e revenue CAGR of 81% and a net profit CAGR of 330%; initiate Buy with a PEG-based TP of RMB758.00

Robotechnik, automating photonics manufacturing

We believe the photonics business will be the key growth catalyst for Robotechnik. The acquisition of ficonTEC in 2025 has given the company a key position in the photonic manufacturing value chain as the technology moves toward high-volume production. Customers include TSMC, Broadcom, and Nvidia (source: prospectus, annual report), giving Robotechnik significant exposure to co-packaged optics (CPO), an emerging photonics technology that allows data centres to pack much more data throughput into a tiny space, which is critical for AI and machine learning clusters.

Robotechnick's fiber-coupling equipment and optical testers are the most important tools in terms of cost and production yield

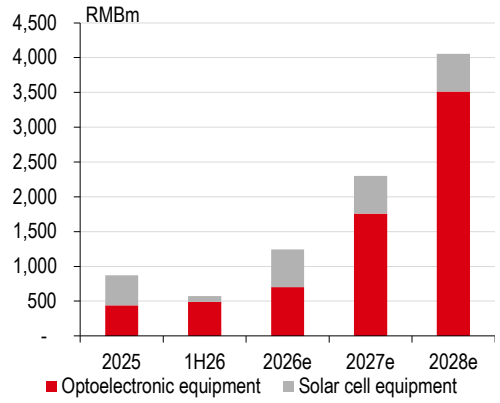
Robotechnick's fiber-coupling equipment and optical testers are the most important tools in terms of cost and production yield (*Exhibit 14*). Fiber-coupling machines can make up to 40% of a production line's value, and testers around 27% (source: Sihan.com), showing how hard it is to scale fiber-to-chip coupling. Demand for testing is driven by the need for fast, high-volume electrical and optical probing, nanometre-level positioning, and active alignment.

Strong order momentum

Robotechnik has announced a series of sizable optoelectronic orders since 2025 (*Exhibit 3*), with an aggregate value of RMB1.7bn y-t-d 2026 vs RMB358m in 2025. They include a RMB600m coupling machine contract, a single-sided tester and a double-sided testing machine. At the 1H26 results, the company announced that its optoelectronic order backlog reached RMB2,452m (at end-June 2026, 72% of the total; orders for the legacy solar cell business totalled RMB934m.

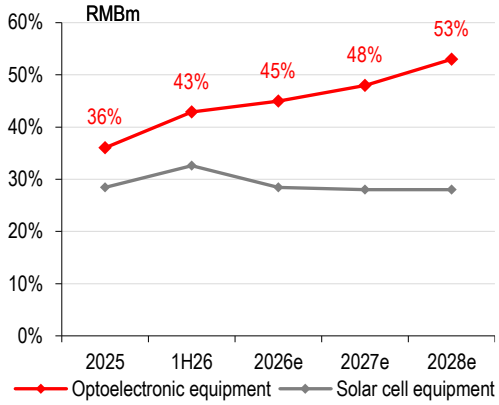
In our view, the order size and mix provides important and early validation of the company's capabilities and customer engagement in the supply chain. It also provides visibility to revenue outlook for 2027, ahead of anticipated photonic mass production from 2028 (*Exhibit 20*). We believe the growing customer engagement, ecosystem partnership, and order visibility will create an inflection point for earnings in 2027.

Exhibit 1. Robotechnik revenue mix forecast



Source: Company data, HSBC Qianhai securities estimates

Exhibit 2. Robotechnik gross margin forecast



Source: Company data, HSBC Qianhai securities estimates

Exhibit 3. The orders announced by Robotechnik since 2025

Date of announcement	Customer	Contract size	RMB	Details
2025				
24 Jun	Top US company A	EUR17.1m	130.5m	Equipment and service
14 Jul	Top US company B	USD14.18m	95.3m	Equipment and service
3 Sept	Swiss company C	EUR9.47m	72.2m	Automated photonics packaging production line
17 Oct	Domestic solar company D	RMB761.5m	761.5m	Solar production line
21 Oct	Wuhan Yilutong Tech	USD9m	60.5m	Fiber preparation and assembly automation equipment
Subtotal			**1,120m**	**RMB358m excluding solar orders**
2026				
6 Jan	Swiss company C	EUR7.7m	58.8m	Second automated photonics packaging production line
27 Jan	NASDAQ-listed Israeli company E	USD9.2m	61.9m	Single-sided wafer test equipment and service
17 Mar	Not disclosed	EUR6.08m	46.4m	Second double-sided wafer test high-volume equipment and service
25 Mar	NASDAQ-listed company F and its China subsidiary	RMB600m	600m	Coupling machine and service
2 Apr	NASDAQ-listed company F	USD35.7m	246m	Coupling machine and service
6 May	NYSE-listed company B	USD26.8m	183m	Test equipment, coupling equipment
	NASDAQ-listed company F	USD32.3m	220m	Vision test equipment, laser assembly equipment
20 Jul	Global auto electronic company G	EUR15.9m (incl 19% VAT)	121m	Automotive camera assembly and test complete line and service
27 Jul	NYSE-listed company H's subsidiary	EUR16.7m	129m	Fiber array unit and optical components high-volume automated equipment and service
19 Aug	NASDAQ-listed company I	USD16.2m	109m	High-volume coupling machine and service
Subtotal			**1,758m**	**RMB1,636m excluding automotive orders**

Source: Company data, HSBC Qianhai Securities

Integration of optical coupling, fiber handling, automation and process know-how – a powerful combination

Photonic alignment expertise, fiber handling, automation integration, and process know-how are essential for scaling optical manufacturing to high-volume production. Optical coupling is limited by fiber-to-chip physics, so active alignment is needed to maximise coupling efficiency while still keeping throughput and yield high (*Exhibits 16-18*). Robotechnik's integrated coupling platforms (*Exhibit 4*) bring together sub-micron accuracy, active alignment, and machine-learning-based process control, creating a distinctive solution that's hard to replicate or replace at scale.

Exhibit 4. Leading photonics alignment component and equipment manufacturers

			Alignment		Active alignment mechanism		Positioning	Resolution
Company	**Main advantages**	**Targeted bottleneck**	**equipment**	**Software/ algorithm**	**First light capture, fine search**	**Motion range**	**accuracy repeatability**	**min. incremental motion**
Global players								
Robotechnik/ ficonTEC	End-to-end integration of alignment, bonding and tracking	Reduce coupling time, post-bond shift, process and equipment integration and high-volume throughput	FIBERLINE	PCM software ficonEDGE (machine learning), proprietary auto-align technology	1) Machine vision algorithm and geometric calibration for coarse pre-alignment, 2) multi-axis first light search and using power as positioning parameter, 3) pre-programmed trajectory peak search, 4) adhesive bonding and active tracking, post-bond shift compensation	4-6 axis, ± 4 degrees rotational resolution, throughput 60 units/hour	±0.02μm	5nm linear, 2 arcsec angular
Physik Instrumente	Algorithm-centric, precision motion control components	Reduce coupling time	Fast Multi-Channel Photonics Alignment system	PILightning	1) Machine vision for coarse positioning, 2) algorithm and high-speed area scan for 1st light search, 3) multi-axis multi-channel gradient search (power as positioning parameter) for peak coupling	3-6 axis, 12-17 degree rotation range. <0.3s reaching global maximum after first light, repeatability <0.01dB	±0.06-0.15μm	5nm
Aerotech+Santec +SENKO	High performance motion control and multi-channel optimisation alignment solution	Reduce coupling time	PICAlign™ (Aerotech's iXR3 Motion Controller, Santec's OPM-200 Optical Power Meter, SENKO's detachable PIC Coupler)	Alignment algorithms	1) Multi-axis first light search, 2) Multi-channel data real-time acquisition for peak coupling 3) Multi-channel optimisation	6-axis, alignment to within 0.2 dB of global optimum in < 1s	±0.15 μm (Aerotech's FiberMaxHP multi-axis alignment system)	2nm
Domestic players								
Suzhou Lieqi	China market, cost effective, local customers relationship	-	Alignment equipment for 800G/1.6T transceiver	Proprietary software	-	-	±0.05μm	10nm
Shenzhen Laserx	Cost-effective, in-house linear guide and motion control	-	Dual fiber array aligner	Proprietary software	1) Machine vision for positioning, 2) Spiral scanning algorithms for first light search and locate peak coupling	Throughput 7 minutes per unit	±0.05μm to ±0.3μm	-

Source: Company data, Lieqi prospectus, HSBC Qianhai Securities

Well positioned in emerging photonic testing applications

We think the company will benefit from the growing demand for photonic testing equipment, a market that is still at an early stage. Robotechnik's advantage in insertion-2 and insertion-3 testing (*Exhibit 5*) can leverage its existing photonic active alignment across various optical components and motion control capabilities, together with its partnerships in the testing ecosystem (*Exhibit 19*). The combination of photonic know-how and chip-testing infrastructure leaves the company well placed to capture a significant share of a potentially large market.

Exhibit 5. Optical testing introduces extra layers of complexity

Test stage	**Insertion 1**	**Insertion 2**	**Insertion 3**	**Insertion 4**
Test content	Wafer-level probing on PIC or EIC	Wafer-level, double-sided electro-optical test after PIC+EIC integration	Singulated die, optical engine test	the entire module after co-packaging with network switches or xPUs
	power, loss, dark current	Optical and electro connectivity	Optical-path loss, coupling efficiency, waveguide fcets, and alignment accuracy	Full system functions, heat management, optical loopback
Alignment accuracy	μm	nm	nm	-
Difficulty	Mature methodology	High	Very high	Very high
Players	ficonTEC+Advantest	ficonTEC+Teradyne (WLT-D2 + UltraFLEXplus software)	ficonTEC	ficonTEC (developing)
	Advantest + Formfactor (high-volume TRITON)	Advantest+MPI (Advantest V93000 EXA and MPI DTS650-DI chip-level probe)	Advantest + Formfactor (V93000 Triton + OptoVue Pro)	Teradyne
			Chroma (58721 O/E test)	Chroma (58711 module test)

Source: Trendforce, picmagazine.net, Company data, HSBC Qianhai Securities

Scenarios for the photonic assembly and testing machine market in 2030

It's difficult to assess the size of the total addressable market for photonic assembly and testing machine as the market is still immature. Our analyst, Bingyi Zheng forecasts that by 2027, 1.6T transceiver demand will be 78,782,000 units (*China Technology – AI optical interconnect series 1: How many optical transceivers do we need?* 14 May 2026), which will require high-volume machines for handling multi-channel assembly.

Exhibit 6 shows that if advanced photonic moves to mass production from 2028 onwards (61m units of CPO in 2030e based on Besi's investor presentation), the market for assembly and testing machine could reach RMB30bn and RMB51bn, respectively. Our bear case assumes co-packaging fails to scale in 2030, with Robotechnik's implied revenue dropping to RMB4.8bn from RMB8bn in the bull case. This would also trigger a de-rating of the stock. In our view, the largest downside risk to the company's growth outlook and valuation in the medium term is that advanced photonic packaging fails to grow as fast as we expect.

Exhibit 6. The photonic assembly and testing equipment market – 2030e bull and bear case

Assumption	2027e	2030e bull case	2030e bear case	Remarks
Photonics				
No. of optical transceivers unit (a)	78.782m* Pluggable only	61m CPO only	78.782m* Pluggable+others	Bingyi Zheng's forecasts for 2027. 2030e is based on Besi estimates (2026 investor day presentation)
No. of optical engine* (b)	8	18	8	Broadcom Tomahawk 5 with 8 optical engines per ASIC chip. NVIDIA's Quantum-X photonic platform with 18 optical engines per ASIC chip.
Optical engine assembly machine				
Unit per hour (c)	45	47*	45	ficonTEC presentation for 2026.
Utilisation rate* (d)	75%	80%	75%	
Yield rate* (e)	85%	95%	85%	
Annual production, unit (f)	247,860	310,262	247,860	f =c*24*360*d*e
No. of equipment, set	2,543	3,539	2,542	= a*b/f
ASP RMB/set*	9m	8.5m	7m	Estimates based on Robotechnik prospectus
TAM (RMB)	22bn	30bn	18bn	
Robotechnik implied revenue* (RMB)	2.2bn	3bn	1.8bn	10% market share
Testers (insertion 1-3)				
Unit per hour	36	37.8*	36	Advantest for 2026
Utilisation rate*	75%	80%	75%	
Yield rate*	85%	95%	85%	
Annual production, unit	198,288	248,209	198,288	
No. of equipment, set	3,178	4,423	3,178	
ASP* (RMB/set)	12	11.5	9.6	Estimates based on Robotechnik prospectus
TAM (RMB)	38bn	51bn	30bn	
Robotechnik implied revenue* (RMB)	3.8bn	5bn	3bn	10% market share
Total implied revenue* (RMB)	6bn	8bn	4.8bn	

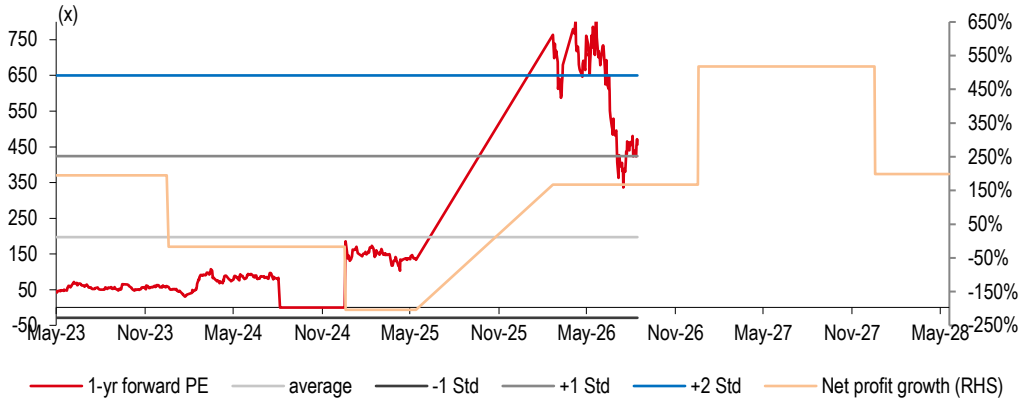
Source: Company website, Besi Investor presentation, HSBC Qianhai Securities estimates*

Valuation and risks

To better capture its near-term fast-growing outlook, we use PEG methodology to value the company. The global peers trade at 0.7x average PEG (based on average 2027-28 PE of 26x with 36% average 2026-28e consensus EPS CAGR). For Robotechnik, we forecast a 330% net profit CAGR in 2026-28e, implying a PE multiple of 231x; applying it to our average 2027-28e EPS of RMB3.29, we arrive at our target price of RMB758.00, implying c37% upside. We initiate coverage of Robotechnik with a Buy rating.

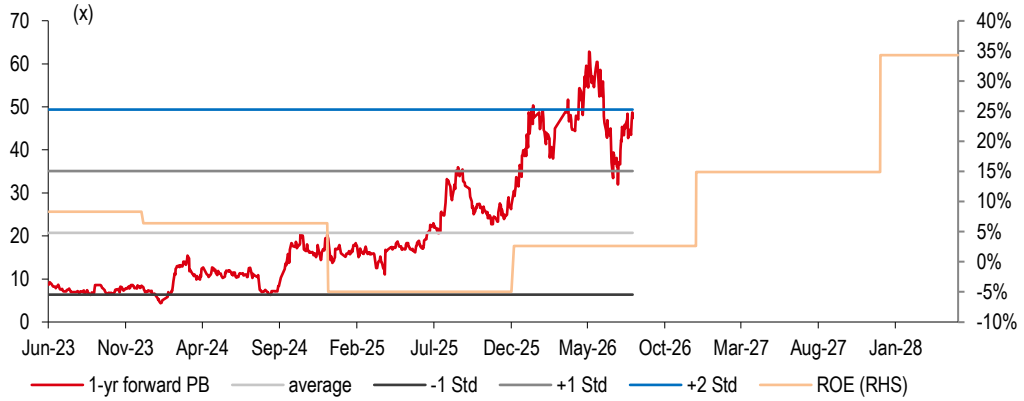
Key downside risks: Alternative coupling solutions, AI capex cuts, slower CPO mass production, geopolitical risks, and price competition.

Exhibit 7. Historical PE with net profit growth



Source: Bloomberg, HSBC Qianhai Securities estimates

Exhibit 8. PB/ROE chart

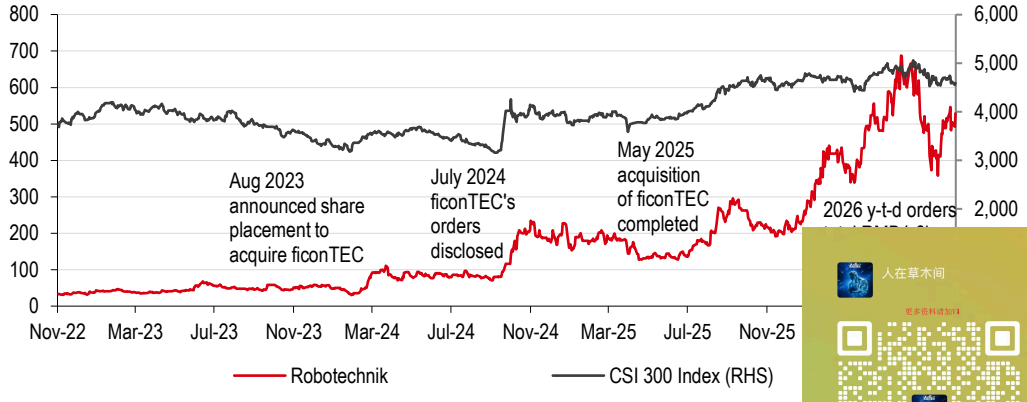


Source: Bloomberg, HSBC Qianhai Securities estimates

Share price performance

Robotechnik's share price has surged 137% y-t-d (vs flattish in the CSI 300 Index), driven by strong AI momentum and robust order growth. The stock corrected 48% between 3 June and 30 July due to the broad de-rating of AI-related high-growth names. It has bounced 54% since 30 July (vs a 2% increase in the CSI300). Despite the rebound, the stock currently trades at 0.6x 2027e PEG, 30% below global peer average of 0.9x 2027e PEG (Bloomberg consensus).

Exhibit 9. Robotechnik share price performance vs index since 2025



Source: Wind, HSBC Qianhai Securities

Valuation comparison table

Exhibit 10. peer comparison table

Company	Ticker	Ccy	Rating	Target price	Price	Market cap USDbn	ADTV USDm	PE (x) 2026e	PE (x) 2027e	PE (x) 2028e	PB (x) 2026e	PB (x) 2027e	PB (x) 2028e	ROE (%) 2026e	ROE (%) 2027e	ROE (%) 2028e	Profit growth 2027	Profit growth 2028	PEG (x) 2027	Net profit CAGR 2026-28e
Robotechnik*	300757 CH	CNY	Buy	758.00	552.11	13.8	594	2069	334.9	112.2	53.9	46.4	32.8	2.6	14.9	34.3	518%	199%	0.6	330%
ASMPT**	0522 HK	HKD	-		165.70	8.9	95.2	39.5	27.2	21.0	3.8	3.4	3.1	10.2	13.1	15.6	45%	28%	0.6	36%
Formfactor	FORM US	USD	NR		110.23	8.6	193.3	36.0	28.3	25.2	N/A	N/A	N/A	18.1	21.3	N/A	28%	10%	1.0	21%
Teradyne	TER US	USD	NR		372.06	58.2	1,577.2	42.2	32.5	25.2	15.7	12.7	9.7	42.0	42.1	42.4	28%	23%	1.1	25%
Besi**	BESI AS	EUR	-		195.00	18.4	133.5	44.5	29.7	22.7	23.4	17.6	14.0	60.3	62.4	65.0	50%	32%	0.6	41%
Mycronic	MYCR SS	SEK	NR		335.80	6.9	8.7	32.5	29.6	25.7	7.9	6.7	5.7	25.8	24.9	24.0	10%	15%	2.9	13%
MPI	6223 TT	TWD	NR		5,090.00	15.7	204.2	77.2	37.6	22.8	27.0	17.1	11.1	39.2	57.9	61.4	105%	67%	0.4	85%
All Ring	6187 TT	TWD	NR		1,430.00	4.4	107.4	48.1	33.5	24.7	14.7	11.6	9.3	32.9	40.5	44.6	54%	33%	0.6	43%
Chroma	2360 TT	TWD	NR		1,990.00	26.7	191.1	44.7	30.5	24.6	19.6	14.7	11.3	50.4	59.9	55.2	46%	23%	0.7	34%
Shibaura	6590 JP	JPY	NR		4,110.00	1.8	67.4	13.5	9.4	N/A	3.1	2.4	N/A	25.8	27.5	N/A	32%	44%	0.5	38%
Advantest	6857 JP	JPY	NR		34,610.00	159.0	1,695.3	29.8	24.9	21.5	13.6	9.8	6.5	54.9	47.4	38.5	28%	19%	1.1	23%
Average								**40.8**	**28.3**	**23.7**	**14.3**	**10.7**	**8.8**	**35.9**	**39.7**	**43.3**	**43%**	**29%**	**0.9**	**36%**

Source: Bloomberg consensus (for non-rated (NR) stocks and GIR covered stocks), HSBC Qianhai Securities estimates (*for rated stocks). **Covered by HSBC Global Investment Research, please go to the HSBC Global Investment Research website for the latest report; Priced as of 27 August 2026.

From solar cells to photonics

- A solar cell automation machine maker transforms into a photonic assembly and testing machine manufacturer
- A core equipment provider in photonic active alignment and test; strong optical, automation and mechanical integration capability
- Deep industry ecosystem relationship with quality global customers

Corporate profile

Robotechnik Intelligent specialises in automated industrial equipment, smart manufacturing execution systems and efficient energy solutions for the solar panel sector. The company was founded in 2011 in Suzhou and listed on Shenzhen Stock Exchange in 2019. It acquired a minority interest in ficonTEC in 2020 and began its expansion into the optoelectronic sector. In May 2025, the company completed 100% acquisition of ficonTEC.

ficonTEC, headquartered in Germany, is a global market leader specialising in the automated equipment for the high-precision assembly, coupling, and testing of optical components. Its equipment are widely used in telecom/datacom, silicon photonics, automotive LiDAR, consumer electronics, 3D sensing, and medical device technologies.

Exhibit 11. Corporate development history of Robotechnik

Year	Milestone
2011	Suzhou Robotechnik was established
2012-14	First plate-type PECVD automated equipment was developed in 2012. Launched an electronic transformer assembly and testing system. Launched various solar cell automation equipment
2019	Listed on the Shenzhen Stock Exchange
2020	Acquired a minority interest in ficonTEC, and began to expand into the optoelectronic sector
2023	Collaborated with ficonTEC to deliver fully automated assembly line for automotive camera systems to an existing customer, Valeo, a leading global automotive electronics and components manufacturer.
2025	Completed the strategic acquisition of ficonTEC for RMB1bn; it is a wholly-owned subsidiary of Robotechnik

Source: Company data, HSBC Qianhai Securities

Exhibit 12. Corporate development history of ficonTEC

Year	Milestone
2001	The company was founded in Germany, by Torsten Vahrenkamp and Matthias Trinker, with the name "ficonTEC" derived from **F**iber **CON**necting **TEC**hnologies to reflect its core focus.
2002-2010	Moved to its headquarters in Achim in 2010 to accommodate its growing manufacturing needs
2006	Expanded its technical capabilities by acquiring the Laser Welding & Automated fiber Alignment business unit from the US-based Newport Corporation.
2011-2019	Global expansion accelerated with the setting up of subsidiaries in Shanghai in 2011, a production plant in Estonia in 2016, Thailand in 2017, and Ireland in 2019.
2021-2022	The 1,000th machine delivery globally in 2022 and established its North American headquarters in Orlando, Florida.
2025	Became a wholly-owned subsidiary of Robotechnik.

Source: ficontec.com, pitchbook.com, HSBC Qianhai Securities

Exhibit 13. ficonTEC's product portfolio

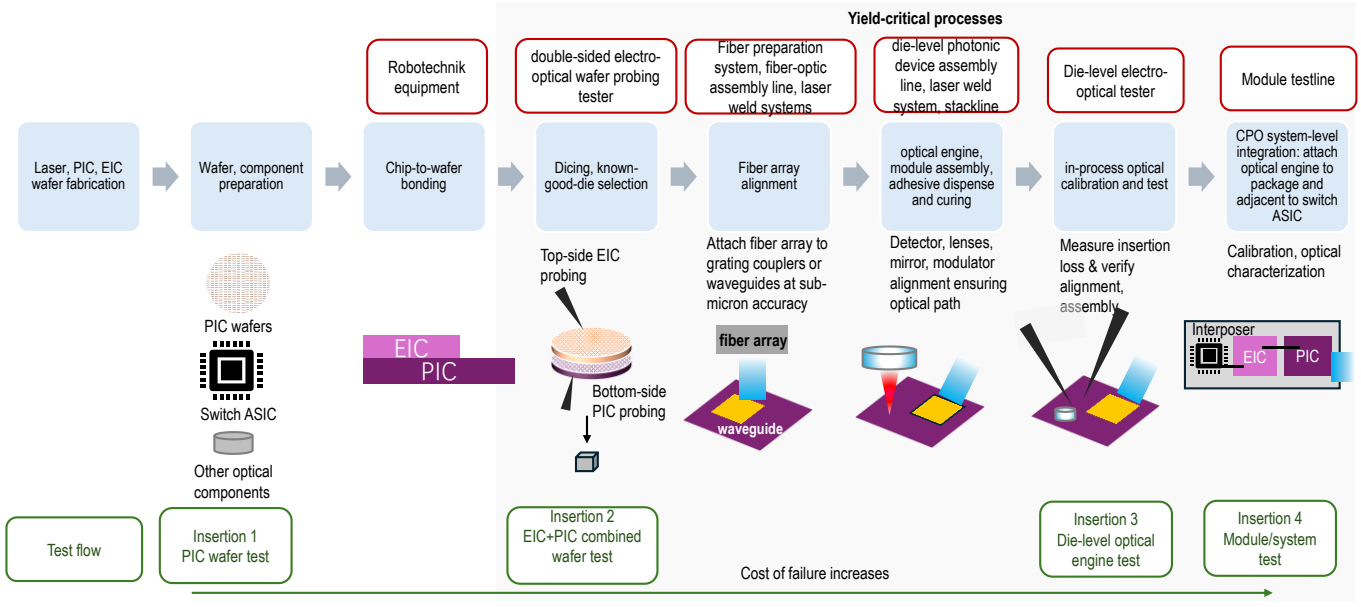
Equipment	Capabilities	Applications	Series	ASP RMBm
Assembly & Bonding	High-precision semi/fully automated sub-micron and nanometer-level die bonding technologies.	CPO chiplets, laser, lens, camera, and LiDAR modules	AL, BL	1.6-4.1
Fiber Coupling	Specialised systems for automated fiber-to-chip coupling and waveguide alignment.	Optical engines, transceivers, CPO modules	FL	1.6-3.3
Laser Welding	Automated laser micro-welding and assembly of high-power laser diode modules	Fiber attach, optical packages, hermetic assemblies	LW	2.1-3.3
Wafer-Level Test	Industry-first high-volume, double-sided electro-optical wafer probing for CPO and silicon photonics. Optical probing, electro-optical characterization, yield analysis	PIC wafers, silicon photonics wafers	WLT	4.1-9.9
Die-Level Test	High-throughput testing of individual photonic dies before final packaging into optical engines. Multi-site (1-3) parallel test handler for double-sided optical engine for max productivity	Optical engines, transceivers, lasers, PIC assemblies	DLT	2.5-6.6
Chip test	For advanced chip-level electro-optical characterization	chiplet		2.5-6.6
Module test	Test complete modules that integrate switch chips with CPO optical engines	completed SiPh module		3.3-5.8
Stack line	Laser bar stacking, micron-level placement	High-power laser modules	SL	2.9-3.3
Custom line	Flexible automation, recipe development, process optimization	Silicon photonics, CPO prototypes, new optical products	CL	2.9-9.9
Fiber preparation line	Automated systems that support the entire preparation process, from fiber stripping, cleaving, MT ferrule insertion, to fiber array unit optical alignment	Silicon photonics, CPO	-	-
Software - Process control master	Process-oriented software control interface, iterating over 20 years of deep learning and field deployment data; enables operators to build complex automated optical test and assembly sequences without needing a background in software engineering.	Controls machine and execute process	-	-
ficonEDGE	A AI layer, embedded within PCM for real-time predictive analytics, proactive maintenance scheduling, and low-latency self-optimization	Machine learnings and optimisation	-	-

Source: Company data, HSBC Qianhai Securities

Equipment for photonic assembly and testing

Unlike mature electrical connections, optical interfaces lack a universal standard for light entry and exit, so highly specialised testing and assembly protocols are required. The problems are compounded by a supply chain that is not yet fully mature. Key bottlenecks centre around how to achieve high-density integration of optical devices with electrical chips with acceptable **yields**, execute precise optical **coupling**, maintain tight **packaging accuracy**, and develop robust **testing** methodologies. We provide an illustration of yield-critical assembly and test process in *Exhibit 14* and show where ficonTEC machines are involved in the process. For a detailed description of silicon photonic chip manufacturing process, refer to the report *China Technology Optics: Silicon Photonics at an inflection point*, 24 April 2024.

Exhibit 14. ficonTEC's machines are used in yield-critical processes in optical assembly and testing



Source: ficonTEC website, onboardoptics.org, HSBC Qianhai Securities

Assembly at scale, a trade-off between efficiency and throughput

According to Robotechnik, the assembly process involves precisely positioning (alignment) one component relative to another and then fixing them together (attachment) with bonding technologies. As data speed increases, chips and components need to be attached with greater accuracy, slowing down its placement rate. Bottlenecks in assembly process are submicron accuracy tolerance, active alignment, fiber coupling and high-volume manufacturing solutions, which collide at the same time in the assembly process and complicate the yield rate.

Exhibit 15. Leading photonics assembly machine manufacturers

Company	EIC-on-PIC* integration via hybrid bonding	Placement precision	Optical engine-on-substrate	Placement precision	FAU/micro-lens attach & active alignment
MRSI	-	-	MRSI-S-HVM	1μm	MRSI-A-L Active Aligner
Besi	2200 Evo advanced to One	3μm roadmap to submicron	2200 Evo advanced to One	3μm roadmap to submicron	-
ASMPT	SEMI hybrid bonding and TCB solutions	±200nm to ±2μm	SEMI flip chip mass reflow solutions	±5μm	-
ficonTEC	-	-	AL, BL, LW, SL series	5nm	FL series

Source: Company data, HSBC Qianhai Securities. Note: EIC refers to electronic integrated circuit, PIC refers to electronic integrated circuit

High-volume fiber coupling and optical assembly machines have emerged as the high-value segment in the photonics supply chain. Robotechnick's equipment and solutions address the mass-production bottlenecks during the integration of electro-optical components. We now explain the basic physics and show why ficonTEC's integrated capability is difficult to replicate.

- **Tight tolerance.** Permissible deviation in positioning optical components that maintains acceptable system performance and power transmission. Micron scale is the permissible tolerance in optical positioning (*Exhibit 16*). It means if fibers, waveguides, and lenses are off by less than a micron, it could lead to measurable and significant signal degradation and loss.

Exhibit 16. Tighter placement tolerance in advanced photonic manufacturing vs pluggable transceiver

Pluggable optical transceiver	Placement precision	Co-packaged bonding steps	Placement precision of ASMPT
DSP & Passive Component Attach	±15μm to ±25μm	EIC-on-PIC integration via hybrid bonding	±200nm to ±2μm
Transmitter & Receiver Attach	±2μm to ±3μm	Optical engine-on-substrate	±5μm
Chips on Submount Assembly	±3μm	FAU/micro-lens attach	±500nm to ±1μm
Electrical & Optic Accessories	±5μm to ±15μm		

Source: ASMPT 2Q26 PPT, HSBC Qianhai Securities

- **Active alignment & fiber array unit** (FAU). The most time-consuming step that is critical to yield, scalability and manufacturing costs, require sophisticated alignment hardware and algorithms. Active alignment is the process of adjusting optical components (lens, sensors, fibers) with real-time feedback from an optical power meter providing data, ensuring coupling efficiency. Fiber array alignment refers to the precise positioning of fibers to couple light with photonic chips, waveguide or other optical devices, allowing the chip to utilise light.

  A single-mode optical fiber core is 8-10μm in diameter (such as Cornings's SMF-28 single-mode fiber with a 9.2 μm core diameter) vs adult hair's 50-100μm and a silicon waveguide cross-section size of 500nm wide by 220nm thick in the silicon photonic device, per The Fiber Optic Association. Coupling between fiber and waveguide is a challenge due to mode mismatch. In fiber optics, the mode field diameter is the actual physical width that a beam of light occupies as it travels down a single-mode fiber, which is important in understanding light loss during coupling into or out of a fiber, per Corning website. Coupling efficiency drops off significantly with misalignment (mode diameter change is positively/negatively correlated to lateral/angular alignment tolerance), in which case tolerances accumulate faster than passive alignment/mechanical fixtures can compensate for.

Exhibit 17. Fiber-to-chip alignment tolerance

Coupling	Mode field diameter change	20% coupling efficiency loss (or 1dB*) from	Advantages	Drawbacks
Fiber to fiber	10.4μm to 10.4μm	2-2.5 μm lateral misalignment, 2-degree angular tilt	-	-
Fiber to grating coupler (light enters from top)	10.4μm to 10μm	2.5 μm lateral misalignment, 2-degree angular tilt	Higher fiber density per optical engine, easier fabrication, wafer-level test	Low coupling efficiency, limited wavelengths, polarization sensitive
Fiber to edge coupler (light enters along the chip)	10.4μm to 3.5μm (via converter)	1-3 μm lateral misalignment, 2-degree angular tilt	Low coupling loss (<20%), mainstream in pluggable transceivers	Complex fabrication, limited fiber density
Fiber direct to waveguide	10.4μm to below 1μm	Very high loss from mode-area variation	-	-

Source: Corning website, sintechcomjournal.com, opg.optica.org. Note: we use Corning's SMF-28 fiber's 10.4 ± 0.8 μm mode field diameter at a wavelength of 1550nm for illustration; *A coupling loss of 1 decibel corresponds to an optical coupling efficiency of 80% (10^(-1/10).

Alignment solutions. Passive alignment uses mechanical pick-and-place to position fiber against a chip, which is fast but with low precision. In contrast, active alignment relies on computer-controlled precision, nanometer high-precision motion control (e.g hexapod device, piezo-stage, linear motor) and data from an optical power meter to optimise coupling efficiency. Alignment equipment temporarily powers up laser or inject external reference light. Its motion system scans the array across six degrees of freedom (X, Y, Z and pitch, yaw, roll per epoxysetinc.com), starts closed-loop real-time feedback via vision systems and sensor and begins adjusting fiber into the position of peak coupling efficiency before fixing it with adhesives. After fixing, the system will re-measure to confirm no misalignment during adhesive. The real-time feedback is essential as coupling efficiency must be verified before optical engine being permanently packaged onto switch. Each CPO module may require 100+ active alignment operations (source: Senko company website, 13 Jan 2026). In high-volume production, the challenge is achieving perfect alignment repeatedly with consistent accuracy and short cycle time. A detailed peer comparison on active alignment in *Exhibit 4* and order mix (*Exhibit 3*) highlights ficonTEC's leading integration capability of fiber handling, active alignment, precision control and automation in this segment.

Exhibit 18. Alignment methods comparison

	Manual alignment	Passive alignment	Automated active alignment
Basic	Worker manually moves component while monitors optical output	Mechanical fixtures (v-groove) determine position	Multi-axis nano-positioning stages, built-in algorithm drives until max coupling
Feedback	Worker + optical power meter	No real-time data	Optical power meter
Determining position	Worker	Predefined mechanical reference	Machine vision, closed-loop optimization
Multi-channel alignment	Difficult	Possible	Advanced controls for multiple channels and degree of freedom
First-light detection	Worker manually searches	Predetermined	Different approaches
Yield, throughput	Low	Can be high for simple assembly	High
Advantages	Low cost	Fast, low cost	Achieving precision, automation, yield
Disadvantages	Slow, labour-intensive	Require high-precision mechanical fixture	Expensive, algorithm complexity

Source: Physik Instrumente website

Optical testing, a new challenge

Photonics manufacturers have a strong economic incentive to shift testing and catch failures at an early stage (*Exhibit 14*) because scrapping a fully packaged module is much more costly than screening a known-good die. That said, testing remains a significant hurdle to the mass production of photonics, as: 1) there is a lack of optical probing standards; 2) simultaneous electrical and optical probing with nano-meter precision alignment causes a single PIC inspection to exceed 100 seconds (source: Trendforce.com, 24 April 2026); and a 3) high level of customisation requires a fundamental redesign of test equipment with automated handlers, sockets, fixtures, and insertion strategy. Advantest breaks down the process into the following four stages (source: Advantest investor presentation, 6 October 2025):

- **Insertion 1** (PIC/EIC Wafer): The PIC wafer is screened using electrical and optical parametric measurements to establish known-good die at the earliest possible stage. This proactively prevents the costly integration of defective silicon into downstream high-value assemblies.

- **Insertion 2** (PIC + EIC integration): This occurs after bonding photonic and electronic ICs, marking the first stage of multi-die integration. It measures electro-optic transfer characteristics at speed, ensuring that the bonding process has not degraded performance and verifies connectivity. PIC and EIC are bonded face-to-face. EIC probing occurs on top while PIC probing contacts simultaneously on the bottom side. No existing test equipment can do this (PhotonCap.com, 8 May 2026).
- **Insertion 3** (Optical engine): This occurs after fiber is attached, when optical engines go through final calibration and functional testing. It becomes more complicated, as coupling conditions change from die to die across various optical components and optical alignment must be optimised separately for each die. This requires multi-axis nano-meter positioning and fast active alignment.
- **Insertion 4** (Packaged module/system): This is the final test insertions, validating overall system functionality for CPO XPUs.

The major automated test equipment players are Teradyne and Advantest. Their advantage is their high-density instrumentation and multi-site architecture, allowing one test program to run across multiple devices. Software systems and long-established industry relationships are also considered advantageous. The market incumbents form partnership (*Exhibit 19*) with photonics experts in the development of optical test equipment. Teradyne believes the total addressable market expansion opportunity for photonics test could reach USD300m-700m per year over the medium term (Teradyne 1Q26 earnings call, 29 Apr 2026). According to Formfactor estimates (Investor day presentation, 11 May 2026), the addressable market size is roughly at USD400m for wafer-level test insertion 1.

Robotechnik's insertion 2 and 3 test equipment are already in mass production

Based on company announcement on 21 July 2026, Robotechnik's insertion 2 and 3 test equipment are already in mass production and shipped to customers while insertion 4 equipment is under development. Insertion 4 equipment possesses the highest price given its multiple parameter capability, followed by insertion 3 and 2. Quantity-wise, insertion 3 equipment is the highest.

We think the company has a strong competitive advantage in insertion 2/3 test equipment, especially insertion 3 test. Insertion 2 test requires simultaneous probing on both sides of the wafer, electrical contacts on the top, optical coupler on the bottom side. The company's double-sided wafer-level tester leverages its strength in multi-axis sub-micron optical alignment that allows double sides probing of a wafer at once. For insertion 3 test, the same architecture extends to the die level but gets more complex as coupling conditions change from die to die across various optical components and different angles, demanding deeper understanding of fast active alignment. With its die-level and wafer-level test equipment in mass production, we think Robotechnik sits in a unique position in the development of photonic test as its equipment and expertise has a greater commercial and financial impact on the photonic supply chain.

Exhibit 19. Leading companies form partnerships to develop photonics test solutions

Companies	Time of release	Co-development focus	Testing stage
FormFactor + Advantest	Nov-24	High-volume SiPh/CPO wafer-level test cell integrating FormFactor's Velox probe station control with Advantest's V93000 tester platform	Insertion 1
FormFactor + Advantest + Tokyo Electron	Oct-25	TRITON system, as industry's first HVM-ready CPO production test cell; ramp accelerating through 1Q 2026, 160+ systems installed globally in 2025-26	Insertion 1
FormFactor + Keystone Photonics (acquisition)	Dec-25	Optical probing technology for SiPh and CPO wafer test	Insertion 1
Advantest + ficonTEC	Jun-25	Single-sided electro-optical wafer-level tester, a first-of-its-kind solution fully compatible with Advantest architectures	Insertion 2
Advantest + OpenLight	Jun-26	End-to-end high-volume electro-optical device (optical engine) test solutions for photonic devices	Insertion 1-4
Advantest + Technoprobe	Nov-25	Probe card co-development for high-performance, comprehensive testing solutions	n.a
Teradyne + Quantifi Photonics (acquisition)	May-25	Photon 100 opto-electric PIC test platform launched in March 2026; supports wafer, optical engine, and CPO test insertions	Insertion 1-4
Teradyne + ficonTEC	Mar-25	Double-sided electro-optical wafer probe test for CPO, integrating UltraFLEXplus equipment and IG-XL programming with ficontec's optical alignment, probing, and wafer-handling tech	Insertion 2-3
Teradyne + MultiLane (JV)	Jan-26	Multilane Test Products address copper connection test in data center	n.a

Source: Company data, HSBC Qianhai Securities

Progress check

Our analyst Bingyi Zheng has highlighted CPO disruption risk for pluggable transceivers from 2028 which warrants monitoring, although she expects pluggable modules to remain the dominant form factor for scaling networking through 3.2T (*China Technology, AI optical interconnect series 1: How many optical transceivers do we need?*, 14 May 2026). The read-across from the major equipment makers is encouraging and confirms a similar 2027-28 inflection point for CPO.

Exhibit 20. Potential 2027-28 CPO inflection point; first photonic test revenue impact in 2025

	Formfactor CPO test system	Chroma	ASMPT	Lumentum
2025	First revenue impacts with qualification and niche production in 2025		-	-
Feb 2026	CPO test system ramp up		-	The company expected first scale-up CPO shipment by 2027
Apr/May2026	Guided 2026 CPO revenue at high end of USD10-20m		-	Scale-up CPO in infancy
Jul/Aug 2026	Guided CPO revenue to be USD20m by 3Q26, and significantly over USD20m for 2026	Major growth driver from photonics. Received order for the Insertion3 and Insertion4O	From the packaging equipment standpoint, the inflection point would be somewhere in 2027-28 for CPO, per company	For scale-up CPO, the company expects shipping in 2H 2027 for customer's deliveries in 2028. There is a broad momentum towards the 2028 ramp of MPO and CPO, driven by optical scale-up

Source: Company data, HSBC Qianhai Securities

SWOT analysis

Strengths

- **Market leader in fiber array unit alignment, with high entry barriers**. Over 20 years' experience in automated high-precision photonic and fiber alignment system design. With an extensive global installation base of over 1,000 machines. The highly-specialised optical components' intellectual properties are very difficult to replicate by competitors, creating high entry barriers.
- **Broad product portfolio and turnkey integration**. The company provides scalable manufacturing equipment and software for fiber preparation, assembly, and welding to testing, covering the majority of the yielding-critical processes of photonics packaging. Leveraging the local supply chain, its expertise in motion control, optical components, manufacturing know-how and proprietary process control master algorithms enables customisation and turn-key automation system delivery. The ability to automate these yield-critical processes and deliver viable product solutions that meet customer requirements enables the company to have first-mover advantage to capture the initial photonic ramp up in a new, growing market that is still developing.
- **Strong ecosystem partnerships**. ficonTEC has an established presence in the optical industry in Europe. This helps the company to engage with customers at an early stage.
- **Capital for capacity scaling**. As an industrial automation equipment maker, Robotechnik has manufacturing infrastructure and purchasing power in the supply chain. It can provide funding, machine tooling, human capital and resources for ficonTEC during the pre-commercialisation period and quickly ramp up production in the future with reduced lead time to fully capture the potential in photonics.

Weaknesses

- More specialised player vs large electronic equipment companies entering the optoelectronic equipment space.
- Relies on third-party mechanical components and motion controllers instead of producing in-house.

Opportunities

- Growing need for automation as photonic integration density increases.
- Booming growth in silicon photonics packaging demand from AI data centres.
- Expanding automation equipment into LiDAR, AR displays, medical sensing chips and satellite links.
- New product lines and solutions in photonic testing.
- China and Asia market access and localisation. Localising the manufacturing of some ficonTEC's equipment could help boost supply volume and provide cost-effective equipment to the market.

Threats

- Cyclicality tied to AI data centre capex.
- Competition: 1) While competition is limited in the fiber coupling machine space globally, larger semiconductor equipment incumbents (*Exhibit 15*, *19*) have stepped up investment to develop photonic assembly and test products; and 2) end customers may develop in-house equipment capability, reducing demand from external suppliers.
- Technical bottlenecks and lower-than-expected yield may push customers to develop alternative approaches.
- Geopolitical frictions in global optical supply chain.

Financials and forecasts

- We forecast a 330% net profit CAGR in 2026-28e, driven by topline growth, favourable product mix and scale effect
- We expect optoelectronic equipment to account for 87% of sales in 2028e from 46% in 2025, supporting gross margin expansion
- Initiate with a Buy rating with target price of RMB758.00

Revenue and GPM

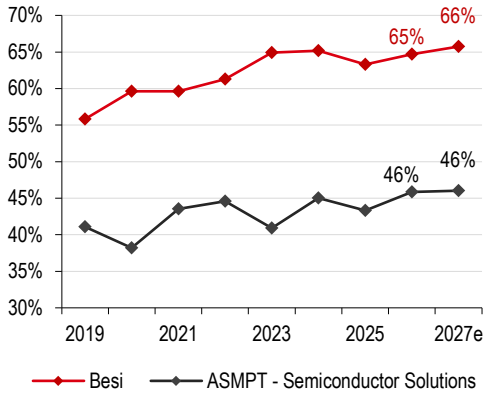
We forecast a 62% revenue CAGR in 2025-28e

Robotechnik's revenue has grown at a 10-year CAGR of 23%, from RMB118m in 2015 to RMB950m in 2025. Growth has been underpined by the boom in the solar renewable energy industry in China and demand for automation equipment. We believe revenue growth is about to accelerate due to a changing product mix. We forecast a 62% revenue CAGR in 2025-28e, driven by photonics coupling, assembly and test automated equipment sales as the photonics industry evolves towards co-packaged optics. Gross margin improved to 34.5% in 2025 from 23.8% in 2019 due to rising sales of optoelectronic assembly and test equipment. This trend should continue. We expect gross margin to improve further to 49.7% in 2028e, similar to peers (*Exhibit 21-24*), supported by rising high-margin order mix and economies of scale.

Optoelectronic assembly and test equipment: This fast-growing segment generated 46% of total revenue in 2025. The segment includes fiber preparation machines, coupling machines, optical component assembly machines, laser welding machines and test machines, as well as complete line systems. We expect revenue to grow 60%, 150%, and 100% in 2026e, 2027e and 2028e, respectively, driven by orders from global optical interconnect and camera players as high-volume equipment shipments ramp up ahead of the introduction of CPO technology in 2028.

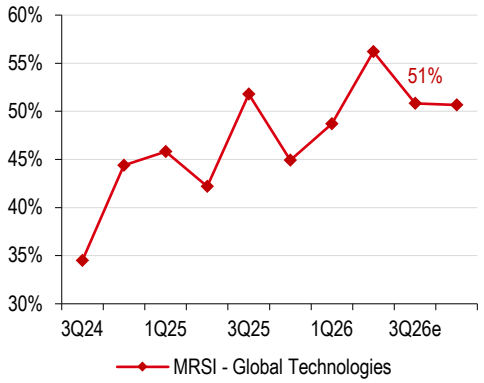
Solar cell automation equipment: This segment accounted for 46% of 2025 revenue. The main products are solar cell manufacturing equipment and intelligent manufacturing execution systems. Global solar installations are no longer growing as quickly, and China's solar demand is weakening before it improves (Corey Chan, *China Solar: Taking a pause*, 28 July 2026). We expect only modest growth in global installations, and softer demand in China as the country shifts to fully market-based renewable energy pricing from June 2025. As a result, we expect the company's solar cell equipment revenue to remain broadly flat over the forecast period, supported by evidence such as an RMB761m order from a domestic customer (*Exhibit 3*).

Exhibit 21. Die bonding equipment maker gross margin – Besi, ASMPT



Source: Company data, HSBC Qianhai Securities; Bloomberg consensus for 2026/27e

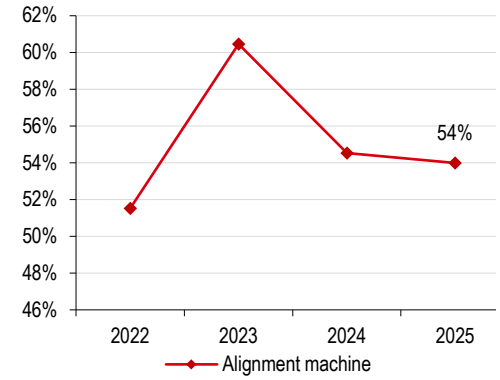
Exhibit 22. Die bonding equipment maker gross margin – MRSI



Source: Company data, HSBC Qianhai Securities; Bloomberg consensus for 3Q/4Q 2026e

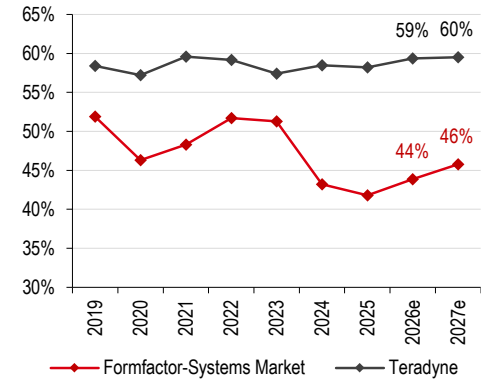
Note: MRSI is part of Mycronic Group, Global Technologies segment include optical communications, PCB test business

Exhibit 23. Alignment equipment maker gross margin – Lieqi



Source: Company data, HSBC Qianhai Securities

Exhibit 24. Test automation maker gross margin – Formfactor, Teradyne



Source: Company data, HSBC Qianhai Securities; Bloomberg consensus for 2026-27e

Exhibit 25. Robotechnik revenue forecasts

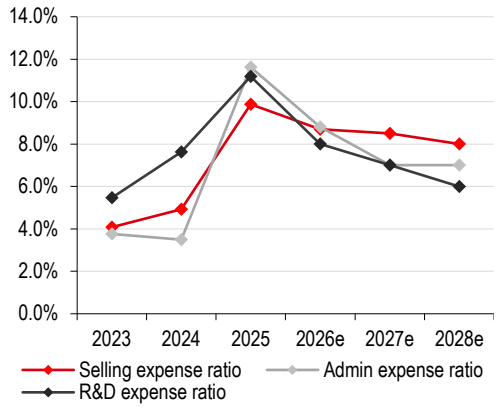
RMBm	2023	2024	2025	2026e	2027e	2028e
Total revenue	**1,572**	**1,106**	**950**	**1,244**	**2,298**	**4,054**
y-o-y	74%	-30%	-14%	31%	85%	76%
Optoelectronic assembly and test equipment	**-**	**-**	439	703	1,757	3,513
y-o-y	-	-	-	60%	150%	100%
Solar cell automation equipment	**-**	**-**	433	541	541	541
y-o-y	-	-	-	25%	0%	0%

Source: Company data, HSBC Qianhai Securities estimates

Operating expenses

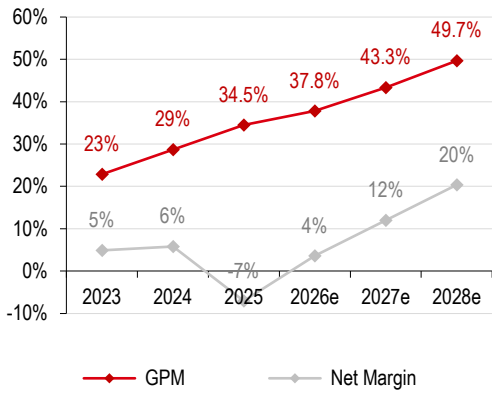
Robotechnik's operating expense ratio surged in 2025 due to a decline in revenue. We expect its SG&A expense ratio to moderately trend down as the revenue contribution from the optoelectronic segment starts to rise and total expenses climb as overseas sales increase. We expect gross margin and net margin to improve during 2026-28e on scale effect, accelerating revenue growth, and the shift in product mix towards optical machines.

Exhibit 26. Robotechnik SG&A expense ratios



Source: Company data, HSBC Qianhai Securities estimates

Exhibit 27. Gross margin and net profit margin



Source: Company data, HSBC Qianhai Securities estimates

Capex and working capital

Robotechnik has limited capex expenditure on fixed assets after 2021 following the downcycle in China solar cell industry. We think the future capex will be directed toward optoelectronic production capacity. Therefore, we expect capex to be at an annual average of RMB166m in 2026-28e vs RMB103m in 2019-21 and RMB25m in 2022-25.

The company's receivable days increased meaningfully in 2025 amid declining revenue and rising optoelectronic business orders, which may increase further as demand of high-volume equipment rises towards 2028. We expect the cash cycle to sustain at current levels in 2026-28e due to revenue growth and a longer delivery cycle.

Cash position and dividend payout

The company recorded RMB284m in cash and cash equivalents at end-2025, accounting for 8% of total assets. It did not distribute a cash dividend in 2025 and we expect no dividends in 2026-28 due to capex to support growth in the optoelectronics business.

HSBC Qianhai Securities estimates versus consensus

Given limited Wind consensus and foreign brokerage coverage, we use average Bloomberg and Wind consensus as reference. Our 2026e estimates are below consensus as we think the current revenue size limits scale effect and profit. 2027 revenue and 2028 net profit estimates are above consensus due to our more positive view on sales of high-volume automated optoelectronic equipment.

Exhibit 28. HSBC Qianhai Securities estimates versus Bloomberg consensus

	HSBC Qianhai estimates			Bloomberg/Wind consensus			Difference		
RMBm	2026e	2027e	2028e	2026e	2027e	2028e	2026e	2027e	2028e
Revenue	1,244	2,298	4,054	1,500	2,157	4,131	-17%	7%	-2%
Net profit	45	276	825	84	283	745	-47%	-2%	11%

Source: Wind, Bloomberg, HSBC Qianhai Securities estimates

Financial statements

Exhibit 29. Income statement

RMBm	2023	2024	2025	2026e	2027e	2028e
Revenue	**1,572**	**1,106**	**950**	1,244	2,298	4,054
COGS	-1,213	-789	-622	-774	-1,303	-2,041
Gross profit	**359**	**318**	**328**	**470**	**995**	**2,013**
Selling expenses	-64	-54	-94	-108	-195	-324
Admin expenses	-59	-39	-110	-109	-161	-284
R&D expenses	-86	-84	-106	-100	-161	-243
Financial costs	-11	-19	-34	-33	-29	-25
Operating income	**83**	**61**	**-71**	**49**	**301**	**900**
Profit before tax	**82**	**60**	**-71**	**49**	**301**	**899**
Less: corporate Tax	-6	3	5	-4	-27	-81
Profit after tax	**76**	**63**	**-66**	**44**	**274**	**818**
Less: minority interest	-1	-1	1	-0	-2	-6.6
Net profit attributable to shareholders	**77**	**64**	**-66**	**45**	**276**	**825**

Source: Company data, HSBC Qianhai Securities estimates

Exhibit 30. Balance sheet

RMBm	2023	2024	2025	2026e	2027e	2028e
Cash & cash equivalents	215	299	264	579	619	1,210
Notes receivable		10	4	5	10	17
Accounts receivable	286	432	674	498	643	811
Prepayments	43	33	5	7	12	22
Inventories	501	205	410	435	460	811
Total current assets	**1,731**	**1,573**	**1,783**	**1,950**	**2,170**	**3,297**
Fixed assets	270	249	251	**2,016**	**2,278**	**2,545**
Construction in progress	22	27	97	97	97	97
Goodwill	8	8	995	995	995	995
Total non-current assets	**836**	**792**	**1,859**	**2,028**	**2,344**	**2,716**
Total assets	**2,567**	**2,365**	**3,642**	**3,979**	**4,514**	**6,013**
Short-term loans	641	923	918	900	700	700
Notes payable	117	1		-	-	-
Accounts payable	523	196	366	426	691	1,061
Contract liability	204	99	157	311	506	811
Total current liabilities	**1,567**	**1,321**	**1,631**	**1,826**	**2,085**	**2,761**
Long-term loans	20	39	303	400	400	400
Total non-current liabilities	**20**	**39**	**340**	**437**	**437**	**437**
Total liabilities	**1,587**	**1,360**	**1,971**	**2,262**	**2,522**	**3,198**
Shareholders' equity	**980**	**1,005**	**1,671**	**1,716**	**1,992**	**2,815**
Total of labilities and shareholders' equity	**2,567**	**2,365**	**3,642**	**3,979**	**4,514**	**6,013**

Source: Company data, HSBC Qianhai Securities estimates

Exhibit 31. Cash flow statement

RMBm	2023	2024	2025	2026e	2027e	2028e
Operating cash flow	-28	-317	208	324	447	793
Investing cash flow	13	-55	-674	-87	-207	-203
Financing cash flow	50	454	433	79	-200	-

Source: Company data, HSBC Qianhai Securities estimates

Valuation

We don't think Robotechnik's historical PE – which reflects its solar cell automation operations – is a good reference point to value the future potential of the optoelectronics business. To better capture its near-term fast-growing outlook, we use PEG methodology. Global peers trade at 0.7x average PEG (based on average 2027-28 PE of 26x with 36% average 2026-28e EPS CAGR, Bloomberg consensus, *Exhibit 10*). For Robotechnik, we forecast a 330% net profit CAGR in 2026-28e, implying a PE multiple of 231x. Applying it to our average 2027-28e EPS of RMB3.29, we arrive at our target price of RMB758.00, implying 37% upside. We initiate coverage of Robotechnik with a Buy rating.

Share price catalysts: accelerating order wins, 3Q26 results beats.

Valuation cross-check

We use sum-of-the-parts as a cross-check for our PEG-based valuation. For the legacy solar cell equipment business, we use the average 2028 PE as of 21 Aug of First Applied Material (603806 CH, Buy, CMP: RMB15.34), Jingsheng (300316 CH, Hold, CMP: RMB45.18) and Xinyi Solar (968 HK, CMP: HKD2.35, *latest report*; PE based on Bloomberg consensus). The 2028 net margin of 5% is derived from the average net margin in 2022-24. For the optoelectronic equipment business, we use global peer average 2028 PE (Bloomberg consensus) and assume the company's 2028 net margin for the business at 20%. We derive a value per share of RMB613, which is below our PEG-based TP but still presents 18% upside to the current share price.

Exhibit 32. SOTP cross-check

RMBm	2028e revenue	2028e net margin	2028e net profit	Valuation multiple	% of SOTP value	Valuation	Remark
Optoelectronic equipment business	1,757	20%	703	162x 2028 PE	90%	102,613	Global peer 2027 average PEG
Solar cell equipment business	541	5%	27	21x 2028 PE	10%	76	2028 average PE of solar companies
Sub-total						102,690	
Net cash						-117	
Value per share (RMB)						613	
Implied upside						18%	

Source: Bloomberg, HSBC Qianhai Securities estimates

Key downside risks

- **Development of alternative solutions to solve optical coupling and assembly.** Emerging technology on high-throughput micro-optical fabrication, such as glass bridge and nano 3D printing, could become a potential threat.
- **Macroeconomic deterioration leading to AI capex cuts.** The company's overseas customers are hardware players in the AI data centre build-out supply chains. If data centre capex slows down, this would reduce demand for Robotechnik's equipment.
- **Geopolitical risks.** Geopolitical tensions between China and the US may limit the company's access to either market, disrupting revenue growth.
- **Advanced photonic packaging commercialisation slower-than-expected**. If the pace of mass production turns out to be slower than the industry's current expectations, 2028 revenue and profit would be materially lower than our current estimates, which could trigger a de-rating.
- **Faster-than-expected pricing competition compressing market revenue despite healthy volume growth.** Emerging technologies, such as CPO, are likely to trigger a change in the competitive landscape, with an increasing number of newcomers. If price competition in assembly and testing equipment is more intense, it could hurt the company's gross margin.

Sustainability

Environmental

The company upholds its environmental responsibilities by adhering to national regulations on conservation and resource efficiency. By integrating these standards with operational reality, the company implements energy-saving measures, adopts efficient technologies, reduces emissions, and maximises resource utilisation.

Social

The company adheres to a "people-oriented" talent philosophy, establishing a multi-dimensional training system aligned with its strategic development and human resource needs. Its onboarding program enables new employees to quickly understand the organisation, embrace its culture, and integrate seamlessly; for existing staff, departments formulate annual training plans based on strategic goals to enhance job competency through professional skills development.

Governance

The company completed the acquisition of ficonTEC and integrated it into its overall internal control framework. By establishing regular reporting mechanisms and other measures, the company enhances supervision and guidance of overseas subsidiaries while respecting local cultures. This ensures compliance with local laws and regulations, while maintaining consistent governance standards and regulatory requirements aligned with the parent company.

Disclosure appendix

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Company	Ticker	Recent price	Price date	Disclosure
ROBOTECHNIK	300757.SZ	536.70	28 Aug 2026	–

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